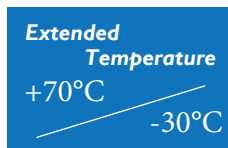


Rugged Embedded Computer

Intel® Q370 Fanless Rugged System with Intel® 9th Generation Core™ i7 Processor, 12V/19 to 28V DC-in, Wide Temp. -30 to 70°C



- Intel® Coffee Lake-Refresh i7-9700TE (8 Cores, 3.8GHz)
- 2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
- 4 x USB3.0, 3 x DisplayPort, 2 x LAN, 1 x Line-out/Mic
- 2 x 2.5" SATA HDD/ SSD Easy Swap Tray
- 4 x COM Port
- Wide range DC-in (12V/19~28V)
- Extended Operating Temperature -30 to 70°C



Specifications ▶

Specifications	
High Performance Processor	Socket LGA 1151 for Intel® Core i7/i5/i3/Celeron® (Supports up to 65W) Intel® Core™ i7-9700TE (8C x 3.8 GHz), 12MB Cache
Memory	2 x SO-DIMM DDR4 2400/2666 MHz up to 64GB
Chipset	Intel® Q370 Chipset
Expansion Slot	- 1x M.2 (Key E, 2230) with PCIe x1 and USB2.0 for Wireless - 1x M.2 (Key M, 2242/2260/2280) with PCIe x4 and SATA3 for SSD (Bottom)
Display	
Display Port	Resolution up to 4096 x 2304 60@Hz
Storage	
HDD/SDD	2 x 2.5" SATA HDD/SSD easy swap tray
Ethernet	
Ethernet	Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps for x2 RJ45 ports)
Rear I/O	
DisplayPort	3 x DP, resolution up to 4096 x 2304
Ethernet	2 x RJ45 Intel® I210 & I219LM GbE LAN (support 10/100/1000 Mbps)
Audio	2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)
USB Port	4 x USB 3.0
Antenna Hole	2
Front I/O	
Power Button	1 x Power Button w/Indicator LED
COM	4 x RS232
Easy Swap SSD Tray	2
Power Requirement	
Power Input	4P Terminal Block, 12/19~28V DC-in

Applications, Operating System	
Applications	Commercial and Industrial Platforms, Embedded Computing, Process Control, Intelligent Automation and manufacturing applications
Operating System	Windows 10 64Bit Ubuntu 16.04 LTS
Physical	
Dimension (W x H x D)	237 x 88 x 293 mm (9.3" x 3.5" x 11.5")
Weight	TBD
Chassis	SECC
Heatsink	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide
Environmental	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
EMC	CE and FCC compliance
Green Product	RoHS compliance
Operating Temp.	-30 to 70°C, Ambient with air flow
Storage Temp.	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing

Ordering information ▶

ROC385B-ET

Intel® Q370 Fanless Rugged System with Intel® 9th Generation Core™ i7 Processor, 12V/19 to 28V DC-in, Wide Temp. -20 to 60°C

ROC385B-UT

Intel® Q370 Fanless Rugged System with Intel® 9th Generation Core™ i7 Processor, 12V/19 to 28V DC-in, Wide Temp. -30 to 70°C

ROC385B

Dimension

